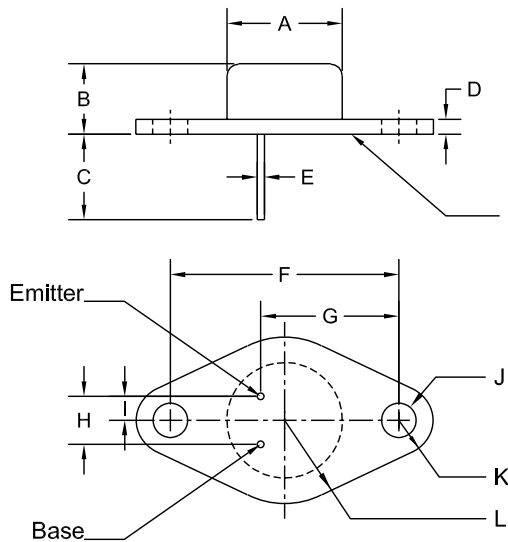


# Package Details - TO-66

## Mechanical Drawing



Seating Plane:  
The seating plane must be within 0.001" concave to 0.004" convex within 0.600" diameter from the center of the device.

SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A (DIA)	0.470	0.500	11.94	12.70
B	0.250	0.340	6.35	8.64
C	0.360	-	9.14	-
D	0.050	0.075	1.27	1.91
E (DIA)	0.028	0.034	0.71	0.86
F	0.958	0.962	24.33	24.43
G	0.570	0.590	14.48	14.99
H	0.190	0.210	4.83	5.33
I	0.093	0.107	2.36	2.72
J (DIA)	0.142	0.152	3.61	3.86
K (RAD)	0.145		3.68	
L (RAD)	0.350		8.89	

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### Lead Code:

As indicated on mechanical drawing.

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### Packing options:

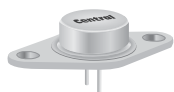
#### Bulk - Packing Code: C

C = Anti-static coated plastic sleeves.

**Bulk Packing Quantity:** 30 per sleeve

# Material Composition Specification

## TO-66 Case



Device average mass . . . . . 5.84 g  
 Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.07%	4.17	doped Si	7440-21-3	0.07%	4.17	714
die coating	Slygard 527	0.66%	38.3	Si	--	0.66%	38.3	6,558
bond wire	aluminum	0.02%	1.15	Al	7429-90-5	0.02%	1.15	197
die attach	high temperature solder	0.37%	21.62	Pb	7439-92-1	0.34%	20	3,425
				Sn	7440-31-5	0.02%	1.08	185
				Ag	7440-22-4	0.01%	0.54	92
header	metal alloy	83.4%	4,871	Fe	7439-89-6	82.6%	4,822	825,685
				Ni	7440-02-0	0.83%	48.7	8,339
can	metal alloy	15.48%	904	Fe	7439-89-6	15.3%	895	153,253
				Ni	7440-02-0	0.15%	9	1,541
can plating*	matte tin**	0.001%	0.06	Sn	7440-31-5	0.001%	0.06	9
termination plating*	matte tin**	0.0001%	0.005	Sn	7440-31-5	0.0001%	0.005	1

\*For Lead Free termination plating, add suffix "LEAD FREE" to part number.

\*\*Contact the Central Semiconductor Sales Department for tin/lead plating availability.

### Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (8-December 2014)